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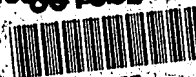
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U.S. UTILITY Patent Application

AUG 26 2003

PATENT NUMBER and

ISS 8510597



6510597

APPL NUM 10060569	FILING DATE 01/29/2002	CLASS 438	SUBCLASS	GAU 1763	EXAMINER Goudreau
** APPLICANTS: Kobayashi Migaku;					
** CONTINUING DATA VERIFIED: THIS APPLICATION IS A CON OF 09/640,959 08/16/2000, now abandoned					
** FOREIGN APPLICATIONS VERIFIED: JAPAN 230500/1999 08/17/1999					
FG-PUB DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials		<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input checked="" type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO N230500C1	
TITLE : Method of fabricating a semiconductor device					
FORMAL DRAWINGS					
ISSUE FEE IN FILE					

NOTICE OF ALLOWANCE MAILED 03/25/03		CLAIMS ALLOWED Total Claims 27 Print Claim for O.G. 1	
ISSUE FEE 276 Amount Due 1600.00 Date Paid 6-24-03		DRAWING Sheets Drwg. 12 Figs. Drwg. 34 Print Fig. 84	
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
PREPARED FOR ISSUE		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

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